U.S. Department of Commerce, Patent and Trademark					Atty. Docket No. Application No.						
INFORMATION DISCLOSURE STATEMENT BY REQUESTOR					SENS.005US1				10/685,550		
REQUESTOR				Applicant(s)					Conf. No.		
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13,	\$		U.S. P	atent Do	cuments						***************************************
Initial		Document Number Date		Name		Cla	ss	Subclass		Filing Date If Appropriate	
	<u>. </u>	<u> </u>	J.S. Published Pa	tent Ann	lication Do	cuments	<u>L</u>				
*Examiner		Document	J.O. I HORDING	tent whh	lication 2.	Cuments	I			Filing D)ate
Initial	. /	Number	Date		Name	Cla	ss	Subcl	ass	If Appropriate	
***	/ 1	2002/0078770	Jun. 27, 2002	Hunter							
<i>X</i> \$	2	2002/0148307	Oct. 17, 2002	Jonkers							-
			Foreign	Patent D	ocuments			·		,	····
		·		,			· · · · · · · · · · · · · · · · · · ·			Trans	slation
		Document	Date		Country	Cla	ss	Subcl	ass	Yes	No
<i>X</i> S	3	WO 03/067183	Aug. 14, 2003		WIPO						
											<u> </u>
	· 	OTHER AF	RT (Including Au	thor, Tit	le, Date, Pe	rtinent Pag	es, Et	c.)			
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		if reference conside mance and not cons									

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		Commerce, Patent		Atty. Docket No.			Application No.
INFORMA	TION I	DISCLOSURE STA	TEMENT BY	SENS.005US1	10/685,550		
OIPE		APPLICANT	<u>.</u>	Applicant(s)	Conf. No.		
14		eral sheets if necess	ary)	Wayne G. Renken	4924		
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PH.	É			October 14, 2003	2856		
TRADEMAN			U.S. P	atent Documents			
Examiner		Document					Filing Date
Initial 88	1	Number RE.32,369	Date Mar. 10, 1987	Name Stockton et al.	Class	Subclass	If Appropriate
	2	5,262,944	Nov. 16, 1993	Weisner et al.			
81	3	5,435,646	Jul. 25, 1995	McArthur	· —		
85	4	 	 		-		
<i>&</i> 3		5,444,637	Aug. 22, 1995	Smesny et al.	+		
<i>X</i>	5	5,564,889	Oct. 15, 1996	Araki			
<i>X</i> 3	6	5,969,639	Oct. 19, 1999	Lauf et al.			
<u> </u>	7	5,970,313	Oct. 19, 1999	Rowland et al.			
	8	6,010,538	Jan. 4, 2000	Sun et al.			
	9	6,033,922	Mar. 7, 2000	Rowland et al.			
	10	6,075,909	Jan. 13, 2000	Ressl			
	11 .	6,100,506	Aug. 8, 2000	Colelli, Jr. et al.			
<i>S</i> 8	12	6,190,040	Feb. 20, 2001	Renken et al.			
	13	6,313,903	Nov. 6, 2001	Ogata			
	14	6,325,536	Dec. 4, 2001	Renken et al.			
	15	6,378,378	Apr. 30, 2002	Fisher			
<i>X</i> 5	16	6,472,240	Oct. 29, 2002	Akram et al.			
X.	17	6,542,835	Apr. 1, 2003	Mundt			
<i>8</i> 8	18	6,553,277	Apr. 22, 2003	Yagisawa et al.			
		U	.S. Published Pa	tent Application Docum	nents	· · · · · · · · · · · · · · · · · · ·	
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>X</i>	19	2001/0014520	Aug. 16, 2001	Usui et al.			
	20	2002/0109590	Aug. 15, 2002	Parsons			
	21 .	2002/0161557	Oct. 31, 2002	Freed			
	22	2002/0172097	Nov. 21, 2002	Freed			
	23	2002/0177916	Nov. 28, 2002	Poolla			
	24	2002/0177917	Nov. 28, 2002	Poolla			
983	25	2002//0193957	Dec. 19, 2002	Freed			
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U.S. Department of Commerce, Patent and Trademark				Atty. Docket No.	Application No				
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)				SENS.005US1	10/685,550				
				Applicant(s)	Conf. No.				
				Wayne G. Renken	4924				
				Filing Date			Group		
				October 14, 2003			2856		
			Foreign 1	Patent Documents					
				•	Transla				
		Document	Date	Country	Class	Subclass	Yes	1	
81	26	WO00/68986	Nov. 16, 2000	WIPO			Abstract		
SS	27	EP 1014437 A2	Jun. 28, 2000	Europe					
83	28	WO02/17030A2	Feb. 28, 2002	WIPO			1		
SS	29	WO02/17030A3	Feb. 28, 2002	WIPO				Г	
				·				-	
		·		·				-	
		· OTHER AR	Γ (Including Aut)	or, Title, Date, Perti	nent Pages, I	Etc.)	<u> </u>		
<i>8</i> 8	30	Prov. Pat. App. No. 60/285,613 filed 4/19/01; Freed et al.; "Firmware, Methods, Apparatus, and Computer Program Products for Wafer Sensors"							
	31	Prov. Pat. App. No. 60/285,439 filed 4/19/01; Freed et al.; "Methods Apparatus, and Computer Program Products for Obtaining Data for Process Operation, Optimization, Monitoring, and Control"							
SS		Products for Obtain	ning Data for Proc	ess Operation, Optimiz	zation, Monit	ornig, and Com			
& \$ ——	32	Products for Obtain Freed et al.; "Auto	nomous On-Wafe	r Sensors for Process Nufacturing, Vol. 14, no	fodeling, Dia	gnosis, and Co			
\$\$ \$2		Products for Obtain Freed et al.; "Auto Transactions on Se	nomous On-Wafer	ess Operation, Optimizers Sensors for Process M	Modeling, Dia	gnosis, and Co 1, pp 255-264.	ntrol," IEEE	ley	
	32	Products for Obtain Freed et al.; "Auto Transactions on Se Freed; "Wafer-Mo Fall 2001	nomous On-Wafer emiconductor Man unted Sensor Arra	r Sensors for Process Mufacturing, Vol. 14, no	fodeling, Dia	gnosis, and Co 1, pp 255-264. ertation, Univ.	ntrol," IEEE	ley	
,83	32	Freed et al.; "Auto Transactions on Se Freed; "Wafer-Mo Fall 2001 International Searce Baker et al.; "A No	nomous On-Wafer miconductor Man unted Sensor Arra h Report, correspo	r Sensors for Process N ufacturing, Vol. 14, no ys for Plasma Etch Pro	Modeling, Dia . 3, Aug. 200 decesses", Diss 0751, 08/01/2	gnosis, and Coi 1, pp 255-264. ertation, Univ.	of CA. Berke		
83 88	32	Freed et al.; "Auto Transactions on Se Freed; "Wafer-Mo Fall 2001 International Searc Baker et al.; "A No Micromachined Se	nomous On-Wafer miconductor Man unted Sensor Arra h Report, correspo	r Sensors for Process Mufacturing, Vol. 14, no ys for Plasma Etch Proporting to PCT/US03/06	Modeling, Dia . 3, Aug. 200 decesses", Diss 0751, 08/01/2	gnosis, and Coi 1, pp 255-264. ertation, Univ.	of CA. Berke		
83 88	32	Freed et al.; "Auto Transactions on Se Freed; "Wafer-Mo Fall 2001 International Searc Baker et al.; "A No Micromachined Se	nomous On-Wafer miconductor Man unted Sensor Arra h Report, correspo	r Sensors for Process Mufacturing, Vol. 14, no ys for Plasma Etch Proporting to PCT/US03/06	Modeling, Dia . 3, Aug. 200 decesses", Diss 0751, 08/01/2	gnosis, and Coi 1, pp 255-264. ertation, Univ.	of CA. Berke		